PRODUCT / PROCESS CHANGE NOTIFICATION

1. PCN basic data	
1.1 Company	STMicroelectronics International N.V
1.2 PCN No.	EMBEDDED PROCESSING/26/16400
1.3 Title of PCN	STM32G544x/534x and STM32G564x/G554x - product enhancement
1.4 Product Category	STM32G564xx, STM32G554xx, STM32G544x and STM32G534x,
1.5 Issue date	2026-10-28

2. PCN Team	
2.1 Contact supplier	
2.1.1 Name	ROBERTSON HEATHER
2.1.2 Phone	+1 8475853058
2.1.3 Email	heather.robertson@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Patrick AIDOUNE
2.1.2 Marketing Manager	Marie TOURNUT
2.1.3 Quality Manager	Pascal NARCHE

3. Change		
3.1 Category	3.2 Type of change	3.3 Manufacturing Location
General Product & Design	Die redesign : Mask or mask set change with new die design like metallization (specifically chip frontside) or bug fix	ST Crolles CR300 (France)

4. Description of change		
	Old	New
4.1 Description	STM32G564x and STM32G554x Current version Cut1.0 ST Crolles (France) die revision “A” STM32G544x and STM32G534x Current version Cut1.0 ST Crolles (France) die revision “A”	STM32G564x and STM32G554x new version Cut1.1 ST Crolles (France) die revision “Z” fixes some limitations listed in device errata ES0656 Rev1, October 2026 Such as : - Allowing to get 10°C more in the application if TAMPER is used, - Less distortion (OPAMP gain error) providing higher precision on the signal amplitude. STM32G544x and STM32G534x new version Cut1.1 ST Crolles (France) die revision “Z” fixes some limitations listed in device errata ES0657 Rev1, October 2026 Such as : - Allowing to get 10°C more in the application if TAMPER is used.
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	functionality enhancement	

5. Reason / motivation for change	
5.1 Motivation	Improvements was implemented to increase robustness, performances and quality of our products.
5.2 Customer Benefit	SERVICE IMPROVEMENT

6. Marking of parts / traceability of change	
6.1 Description	Traceability ensured by ST internal tools. Die revision changes from "A" to "Z" on Package Marking

7. Timing / schedule	
7.1 Date of qualification results	2027-01-11
7.2 Intended start of delivery	2027-01-15
7.3 Qualification sample available?	Upon Request

8. Qualification / Validation			
8.1 Description	16400 MDRF GPAM-RER2415-STM32G55x Die44A-RER2416-STM32G53x Die44B - Reliability Plan.pdf		
8.2 Qualification report and qualification results	Available (see attachment)	**Issue Date**	2026-10-28

9. Attachments (additional documentations)
16400 Public product.pdf 16400 MDRF GPAM-RER2415-STM32G55x Die44A-RER2416-STM32G53x Die44B - Reliability Plan.pdf 16400 _Additional information.pdf

10. Affected parts		
10. 1 Current		**10.2 New (if applicable)**
10.1.1 Customer Part No	**10.1.2 Supplier Part No**	**10.1.2 Supplier Part No**
	STM32G544KCU3	
	STM32G544MCT3	
	STM32G564CET3	
	STM32G564MET3	
	STM32G564QET3	
	STM32G564RET3	
	STM32G564REZ3	
	STM32G564VET3	
	STM32G564VEZ3	

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